

Title (en)
THERMALLY STABLE POLYESTER MOLDING MATERIALS

Title (de)
THERMISCH STABILE POLYESTERFORMMASSEN

Title (fr)
MATIERES MOULABLES POLYESTERIQUES THERMOSTABLES

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Application
EP 00974513 A 20001110

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Abstract (en)
[origin: WO0138436A1] The invention relates to thermoplastic molding materials containing the following main components: A) 2 to 97.9 wt. % of at least one polyester; B) 0 to 95.9 wt. % of at least one polycarbonate; C) 1 to 80 wt. % of at least one graft polymer which is made up of c1) 40 to 80 wt. % of a graft base consisting of a rubber elastic polymer based on alkyl acrylates with 1 to 8 C-atoms in the alkyl radical and with a glass transition temperature of less than 10 DEG C, c2) 20 to 60 wt. % of a graft support consisting of c21) 60 to 95 wt. % styrene or substituted styrenes of general formula (I), wherein R represents an alkyl radical with 1 to 8 C-atoms or a hydrogen atoms and R<1> represents an alcohol radical with 1 to 8 C-atoms and the value of n is 1, 2 or 3 and c22) 5 to 40 wt. % of at least one unsaturated nitrile; D) 1 to 80 wt. % of a copolymer consisting of d1) 60 to 95 % styrene or substituted styrenes of general formula (I) or mixtures thereof and d2) 5 to 40 wt. % of at least one unsaturated nitrile; E) 0.1 to 10 wt. % of an epoxyde resin; and F) 0 to 80 wt. % other additives, the sum of the weight percentages of components A) to F) being 100 %.

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